



# **SPECIFICATION FOR SMT TCXO** MtronPTI P/N M6164S012

### **Electrical Specifications:**

Parameter	Symbol	Min.	Тур.	Max.	Units	Conditions
Frequency of Operation	Fo		50.000000		MHz	
		Fi	requency Sta	bility		
Frequency Stability	∆F/F	-10		+10	ppm	(F <sub>max</sub> – F <sub>min</sub> )/2
Frequency Vs. Reflow		-1.0		+1.0	ppm	
Frequency Vs. Supply			± 0.02	± 0.1	ppm	For 5% supply variation
Frequency Vs. Load			± 0.02	± 0.1	ppm	For 5% load change
			Output			
Output Type		HC	MOS Compat	ible		
Output Load				15	pF	
Symmetry (duty cycle)	T <sub>DC</sub>	40	50	60	%	@ 50% of VDD
Output Logic Levels	Vol			20	% V <sub>CC</sub>	$IOH/IOL = \pm 4 \text{ mA}$
Output Level	V <sub>OH</sub>	80			% V <sub>CC</sub>	$IOH/IOL = \pm 4 \text{ mA}$
Rise/Fall Time				6.5	nS	Ref. 10% and 90%
Tri-state Function			r floating, outp utput Disabled			Pad 8
			tional Specif			
Start-up Time	Τsυ			10	mS	
Phase Noise			-80		dBc/Hz	@ 10 Hz
			-108		dBc/Hz	@ 100 Hz
			-132		dBc/Hz	@ 1 kHz
			-149		dBc/Hz	@ 10 kHz
			-155		dBc/Hz	@ 100 kHz
			tage & Power	Consumptio	on	
Operating Voltage	Vdd	3.135	3.3	3.465	V	
Operating Current	IDD			5.0	mA	

#### **Environmental Conditions:**

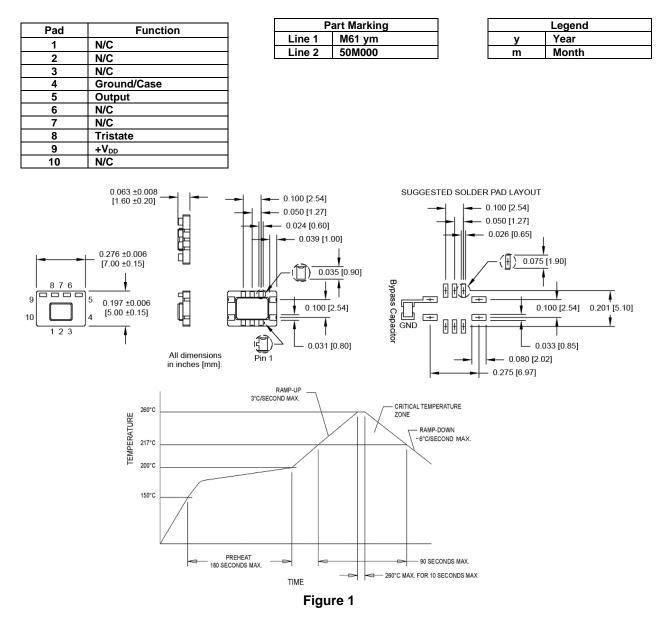
Operating Temperature	TA	-55		+105	°C	
Storage Temperature	Ts	-55		+125	°C	
Mechanical Shock	Per MIL-STD-202, Method 213, Condition C (100 g's, 6 ms duration, ½ sine wave)					
Vibration	Per MIL-STD-202, Method 201 & 204 (10 g's from 10-2000 Hz)					
Solderability	Per EIAJ-STD-002					
Max. Soldering Conditions	See solder profile, Figure 1					
Package Type	5.0 x 7.0 x 2.0mm, 10-pad Ceramic Leadless Chip Carrier. RoHS Compliant.					





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### Mechanical, Marking and Layout Information:



#### **Datasheet Revision Table:**

Date	Rev.	Author	Details of Revision
11/7/13	0	MM	Original Release.